



ATTORNEY DOCKET NO.: SS-714-01

U.S. PATENT APPL. NO.: 09/596,837

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:

Vladimir Vaganov

SERIAL NUMBER: 09/596,837

FILED: June 19, 2000

FOR: Method for Fabricating Microstructures  
with Deep Anisotropic Etching of Thick Silicon  
Wafers

PATENT

ART UNIT NO.: 1763

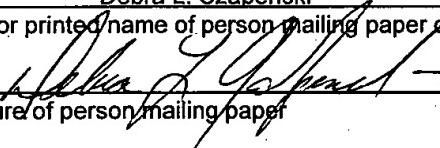
EXAMINER: George Z. Goudreau

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DATE OF THIS PAPER:

MAY 13, 2003

I hereby certify that this Response and the documents referred to as enclosed therein are being deposited with the United States Postal Service as First Class Mail on May 13, 2003 addressed to Attn: Mail Stop Non-Fee Amendments, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450

Debra L. Czapenski  
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Alexandria, VA 22313-1450

## RESPONSE

Sir:

In response to the Office Action mailed March 17, 2003, please amend the above-identified application as follows: